

L Number	Hits	Search Text	DB	Time stamp
1	3434	(chip adj1 chip) and (wire wiring) and (substrate (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/12 15:45
2	7666	(qfp qfn ((flat quad) near1 package))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/12 15:44
3	18209	((qfp qfn ((flat quad) near1 package))) (chip adj1 chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/12 15:45
4	5380	((((qfp qfn ((flat quad) near1 package))) (chip adj1 chip)) and (wire wiring) and (substrate (printed adj circuit adj board))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/12 15:46
5	138299	(first near1 (package die chip device))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/12 15:48
6	1691	((((qfp qfn ((flat quad) near1 package))) (chip adj1 chip)) and (wire wiring) and (substrate (printed adj circuit adj board)) and ((first near1 (package die chip device)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/12 16:07
7	1441	(((((qfp qfn ((flat quad) near1 package))) (chip adj1 chip)) and (wire wiring) and (substrate (printed adj circuit adj board)) and ((first near1 (package die chip device)))) and (mounting mounted)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/12 16:08
8	939	(((((qfp qfn ((flat quad) near1 package)) (chip adj1 chip)) and (wire wiring) and (substrate (printed adj circuit adj board))) and ((first near1 (package die chip device)))) and (mounting mounted)) and (sealed sealing encapsulant encapsulating encapsulated)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/12 16:08
9	432	((((((qfp qfn ((flat quad) near1 package)) (chip adj1 chip)) and (wire wiring) and (substrate (printed adj circuit adj board))) and ((first near1 (package die chip device)))) and (mounting mounted)) and (sealed sealing encapsulant encapsulating encapsulated)) and (test testing tested)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/12 16:09
10	170	((((((qfp qfn ((flat quad) near1 package))) (chip adj1 chip)) and (wire wiring) and (substrate (printed adj circuit adj board))) and ((first near1 (package die chip device)))) and (mounting mounted)) and (sealed sealing encapsulant encapsulating encapsulated)) and (test testing tested)) and pad and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/12 16:12
11	358	((((((qfp qfn ((flat quad) near1 package))) (chip adj1 chip)) and (wire wiring) and (substrate (printed adj circuit adj board))) and ((first near1 (package die chip device)))) and (mounting mounted)) and (sealed sealing encapsulant encapsulating encapsulated)) and pad and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/12 16:10
12	338	((((((qfp qfn ((flat quad) near1 package))) (chip adj1 chip)) and (wire wiring) and (substrate (printed adj circuit adj board))) and ((first near1 (package die chip device)))) and (mounting mounted)) and (sealed sealing encapsulant encapsulating encapsulated)) and pad and electrode) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/12 16:15

13	140	(((((qfp qfn ((flat quad) near1 package))) (chip adj1 chip)) and (wire wiring) and (substrate (printed adj circuit adj board))) and ((first near1 (package die chip device)))) and (mounting mounted)) and (sealed sealing encapsulant encapsulating encapsulated)) and pad and electrode) and semiconductor) not (bum ball)	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/02/12 16:21
14	218	(((((qfp qfn ((flat quad) near1 package))) (chip adj1 chip)) and (wire wiring) and (substrate (printed adj circuit adj board))) and ((first near1 (package die chip device)))) and (mounting mounted)) and (sealed sealing encapsulant encapsulating encapsulated)) and pad and electrode) not ((((((qfp qfn ((flat quad) near1 package))) (chip adj1 chip)) and (wire wiring) and (substrate (printed adj circuit adj board))) and ((first near1 (package die chip device)))) and (mounting mounted)) and (sealed sealing encapsulant encapsulating encapsulated)) and pad and electrode) and semiconductor) not (bum ball))	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/02/12 16:21
15	7	("5181097"   "5665795"   "5683942"   "5708300"   "5726489"   "5729051"   "5841192").PN.	USPAT	2003/02/12 16:28